



Continuous innovation and improvement
All employees pursue excellence

2024 Third Quarter Investor Conference

Stock symbol : 6207

2024/12/18

LASER TEK, TAIWAN CO., LTD.

Disclaimer

The above statements that pertain to future projections constitute the expectations, opinions, outlooks, or predictions of our company and its affiliates based on information available at the time the statements were made. Such statements may be affected by known and unknown risks and inherent uncertainties, the existence or emergence of facts or factors that differ from the assumptions, suppositions, or judgments of the Company, or other factors. Consequently, there may be significant discrepancies between actual results pertaining to the Company's future earnings, management results, financial conditions, and other matters as explicitly or implicitly referred to in the statements and the content of such statements. This representation is run exclusively for the purpose of providing information and not for the purpose of soliciting investments or recommending the buying or selling of specific shares or products. The company makes no warranty concerning the accuracy or completeness of the information and will not be liable for any damages arising out of use of the information hereof.



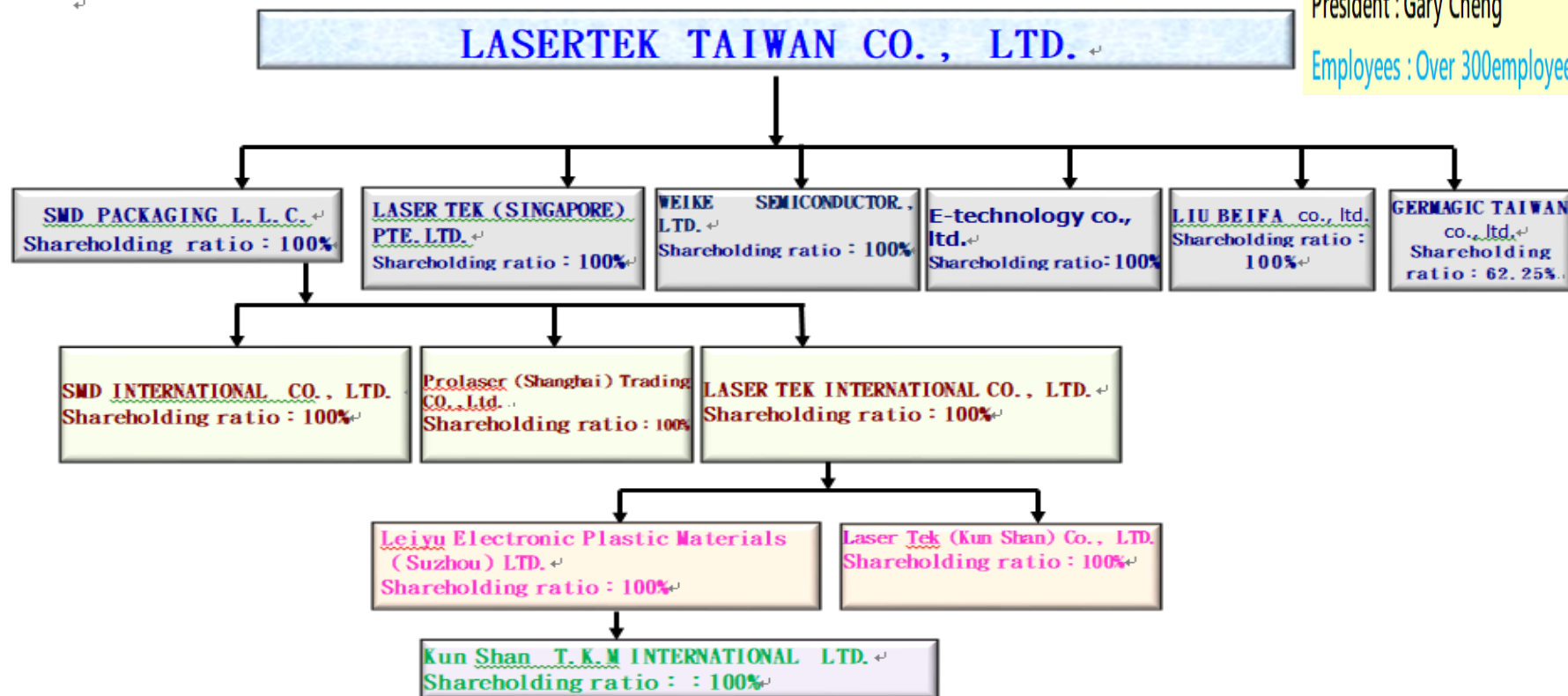
Company Overview

Date of Establishment : Sep 9th, 1988

Capital : 796 Million NT Dollars

President : Gary Cheng

Employees : Over 300 employees Worldwide



Business Location

Global layout, focus on core optoelectronic technology
Expand Niche Blue Ocean market, providing complete service

**Prolaser
(KunShan,
China)**



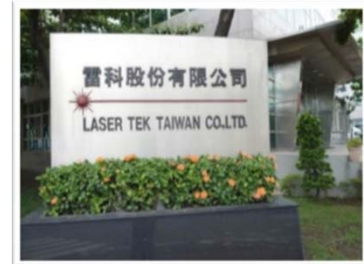
**Warehouse
(DongGuan,
China)**



**Laser Tek
(Singapore)**



HsinChu Branch




LaserTek Headquarter



**Kaohsiung
Hsin Sheng
Building**




Product Business Group




設備事業 (Laser & Metrology Equipments)

LASER Equipment COWOS Equipment




SMD捲裝材料事業 (Surface Mount Device Packaging Materials)

Passive components Packaging Materials Semiconductor components Packaging Materials



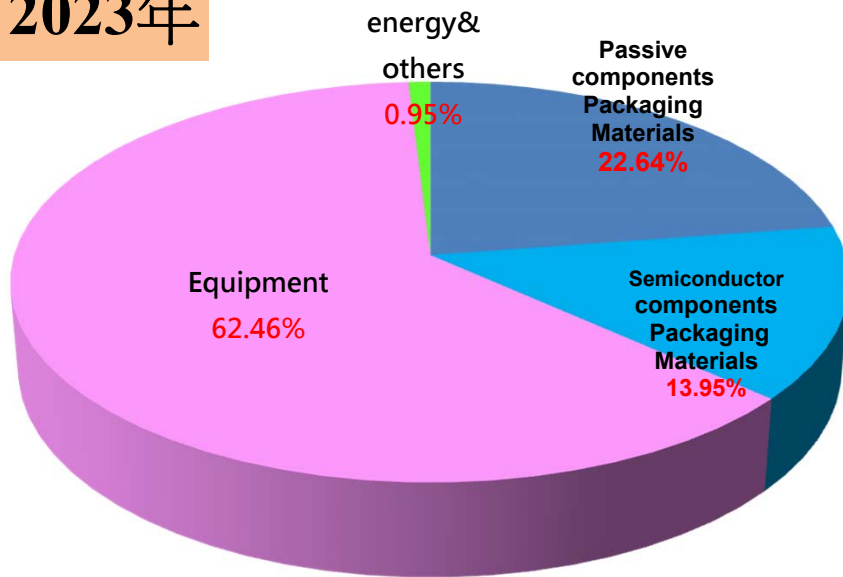
Energy Saving Devices / GERMAGIC防疫產品

Solar energy related businesses Air Purifier GERMAGIC Epidemic Prevention Products

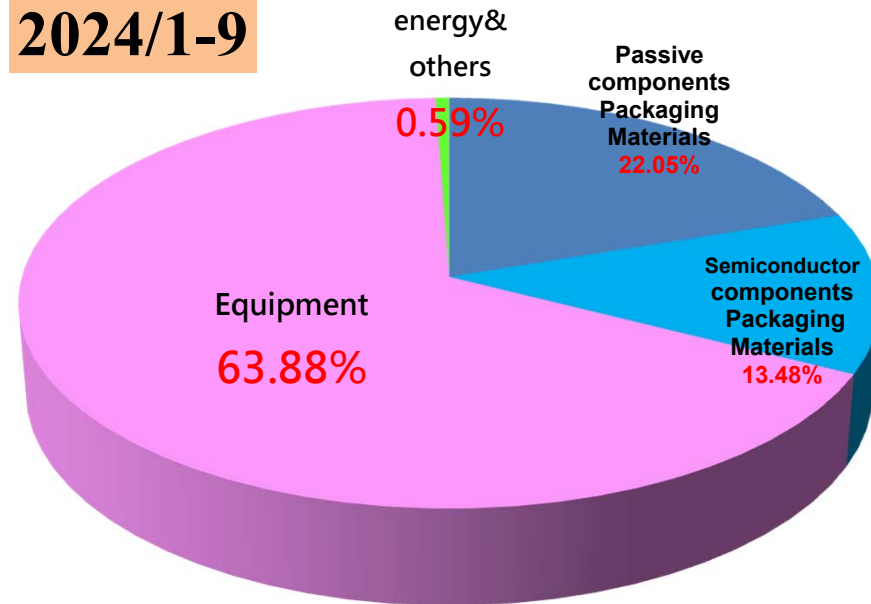


Products revenue share %

2023年

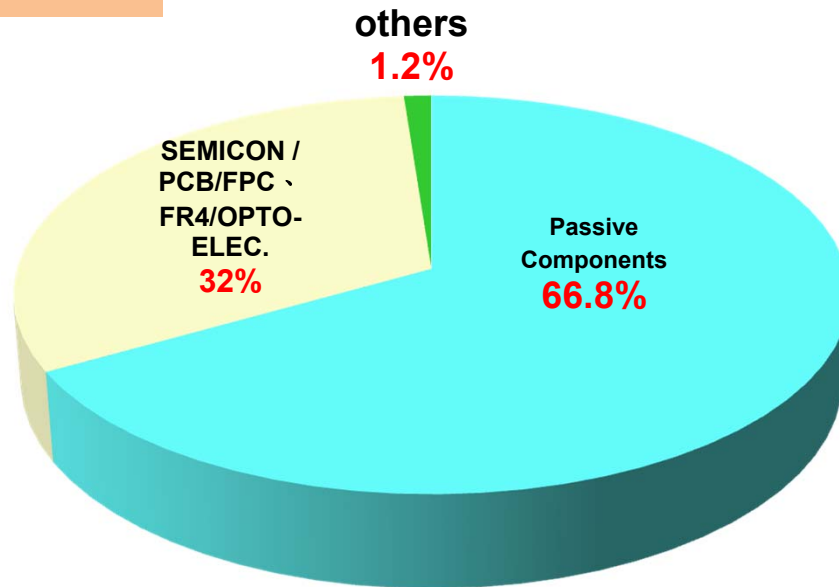


2024/1-9

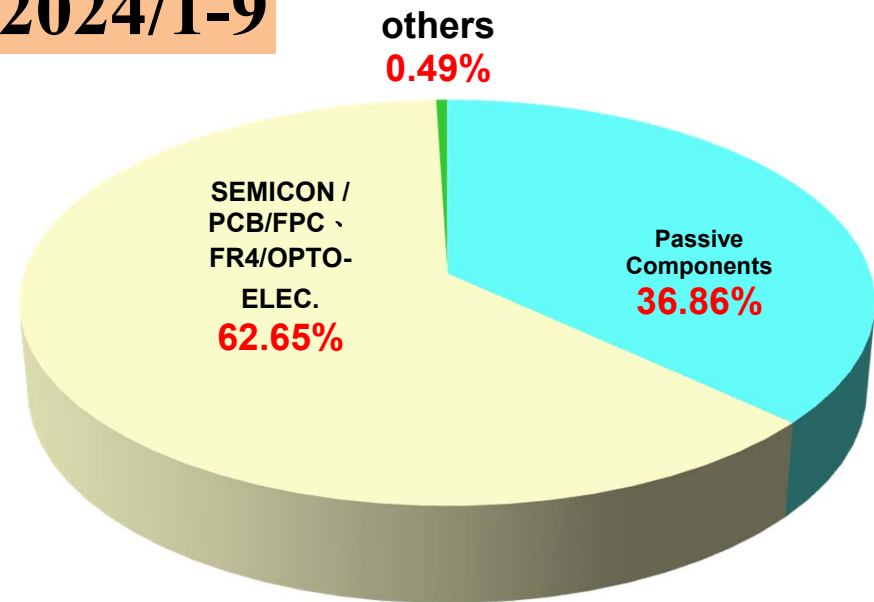


Industry revenue percentage of products

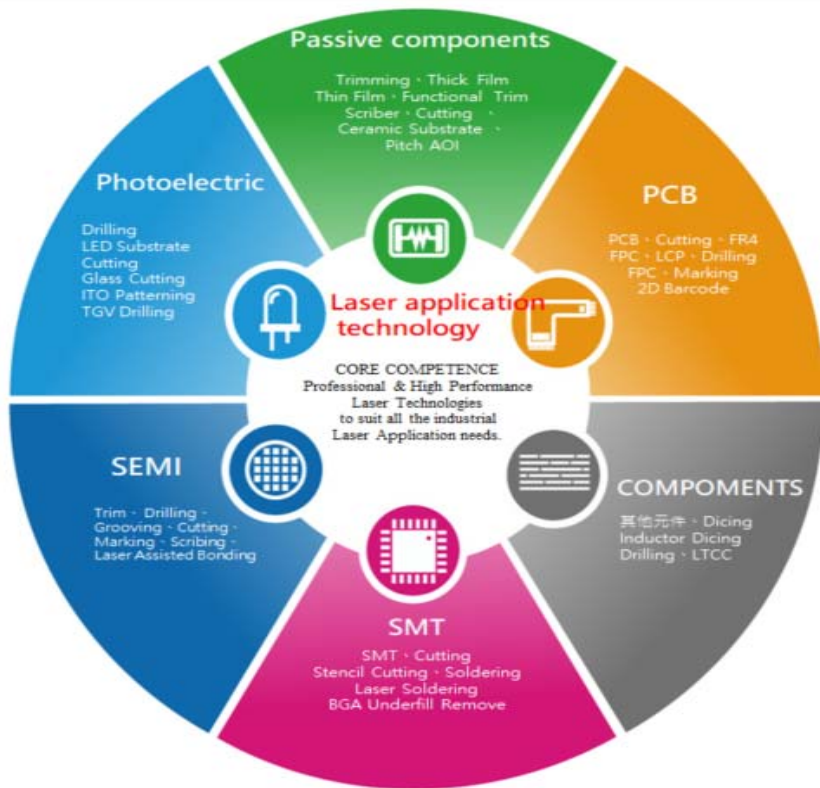
2023



2024/1-9

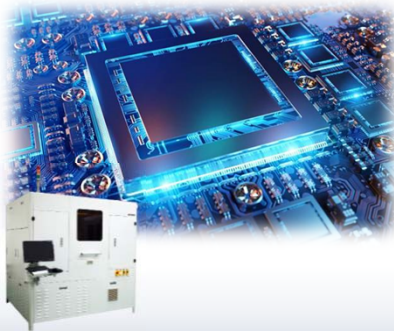


Laser Core Competitiveness & Territory



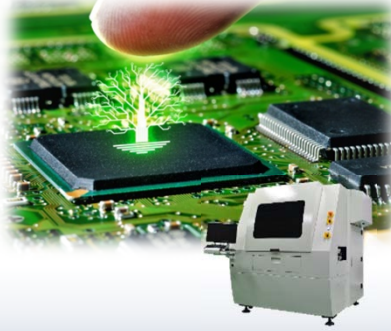
➤ Four Application Field

Semi



- Wafer trim
- CoWoS
- TSV
- SIC cutting
- FOPLP

Substrate



- FR4 automotive electronics
- RF high frequency heat
- 5G high frequency components

component



- Thick film
- Thin film(High precision)
- Functional trim

AI application



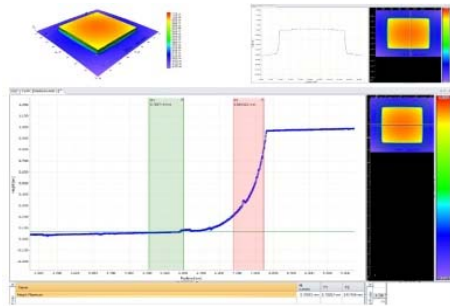
- AI Defect inspection
- AI Diamond cutting
- VR Smart cutting
- AI GPU glue removal



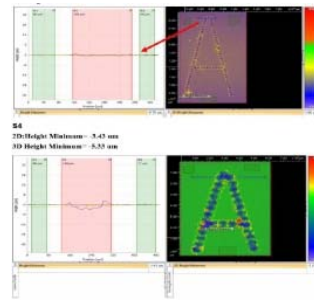


Semiconductor Field

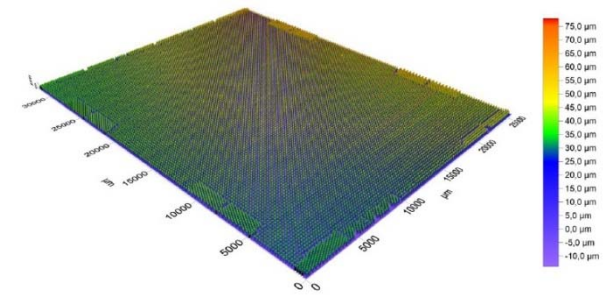
CoWoS Package Measurement



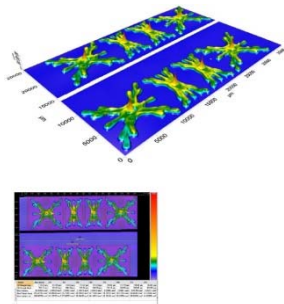
▲ UNDER-FILL GLUE FILLET HEIGHT



▲ LASER SCRIBING

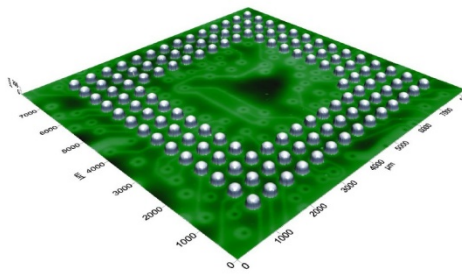


▲ C4 bump height ,diameter & warpage measurement (substrate surface side) by L-CHR

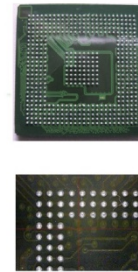


▲ SOLDER DISPENSED

Surface image of a Micro BGA



▲ HEIGHT, COPLANARITY –BGA SOLDER BUMPS



- CTWL200D
 - CT350T
 - CT450T
 - CT600T
- (TTV)



- CT350
- CT450
- CT600



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➤ Semiconductor Field

Laser Equipment--- Front-end cutting & drilling/ Mid-end Test / Back-end Package

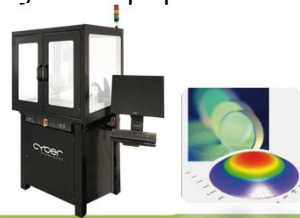
Wafer Manufacture

TSV femtosecond drilling machine



Special optical module for silicon wafers, enabling through-silicon via drilling and blind hole cold processing.

Cyber equipment



High level 2D/3D non-contact surface metrology system.

Mid-end Test

Wafer trim



Semiconductor wafer trimming, Online real-time measurement and trimming.

Functional trim



Hybrid Circuit IC functional trim, high precision measurements, precise trimming.

Back-end Package

FR4 cutting



Assembly & Testing products cutting, Sorter collection, automated assembly line.

Laser Deflash



Deburring of Lead frame, Thermal expansion compensation with four-point alignment.

SIC femtosecond cutting machine



Special optical module for SIC etching and cold processing cutting.

Wafer marking



IC Marking, Wafer Marking

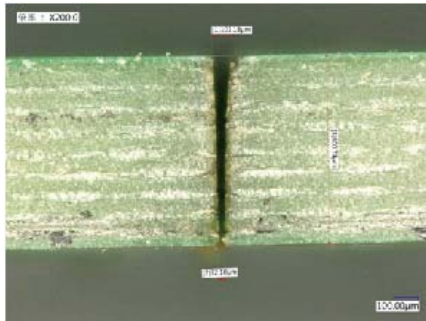
FOPLP



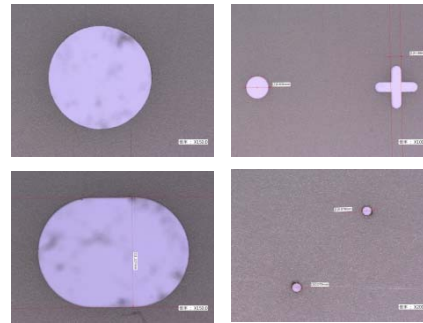
Colloid removal from glass substrate

➤ Substrate Application

Laser application equipment --- Advanced semiconductor packaging substrates / RFPCB



Automotive substrate
Substrate cutting application



High-frequency RF heat dissipation substrate
LEO application



High precision Rigid-flex PCB cutting
Consumer electronic board

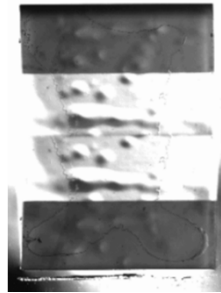


➤ AI Application Laser application equipment --AI+AOI+Laser



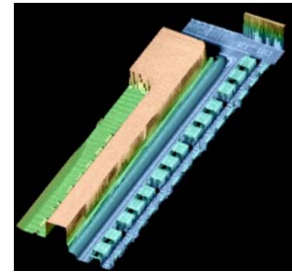
AI defect inspection

Laser Applications in Various Components



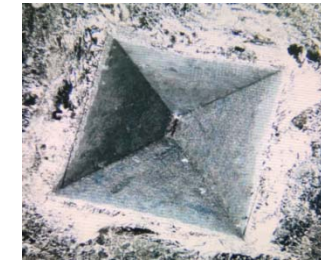
AI Transparent contour construction

VR/AR glass cutting application



AI-generated colloid height profile

AI chip adhesive removal application



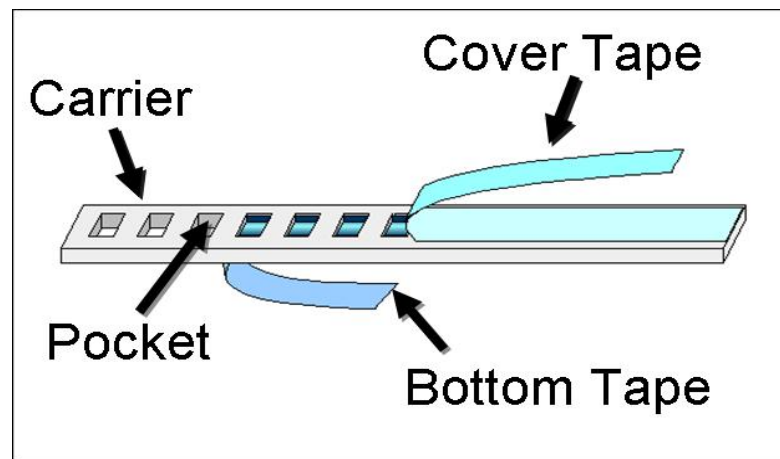
AI Image Recognition

Laser application on reflective materials



➤ Surface Mount Device Packaging Materials

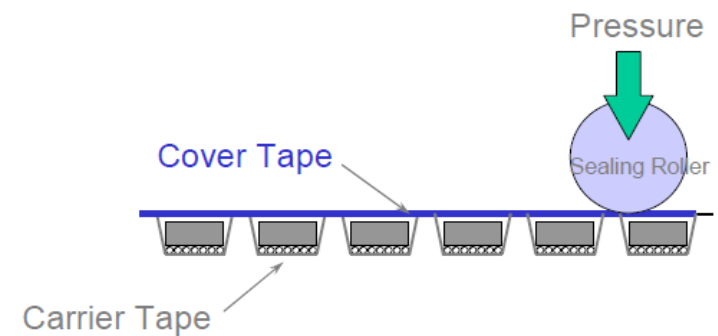
Passive components Packaging Materials



➤ Surface Mount Device Packaging Materials

Semiconductor components Packaging Materials

- Carrier Tape : Packaging tapes for IC semiconductors, electronic passive components, LED products, etc.
- The main materials are PC, PS... and other plastic raw materials.



2024 3Q Operating Performance



Statements of Comprehensive Income Statements of Comprehensive Income

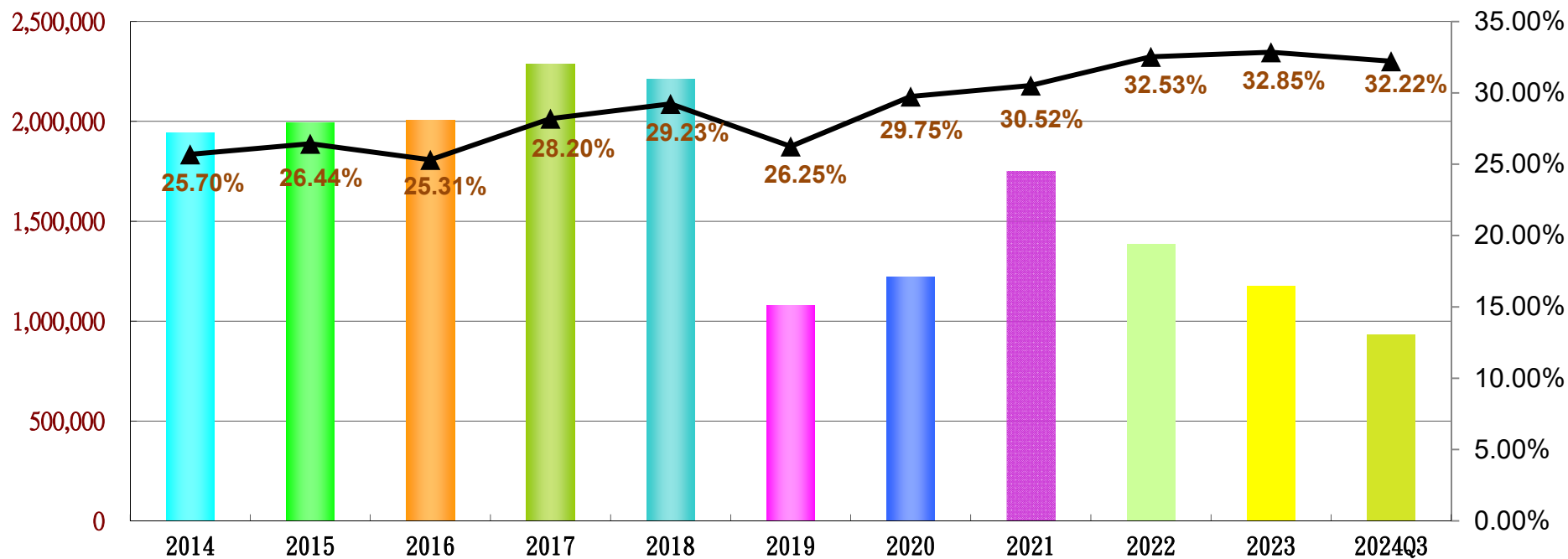
Units : NT\$ Thousand;%

Items	2024 3Q	2023 3Q	2024/3Q Over 2023/3Q
Operating Revenue	935,808	776,739	20.48%
Gross Margin	32.22%	30.63%	5.19%
Operating Expenses	239,291	216,652	10.45%
Operating Margin(Loss)	62,262	21,266	192.78%
Operating profit margin	6.65%	2.74%	142.70%
Non-Operating items	90,656	122,305	-25.88%
Net income(Loss) to Shareholders of the Parent Company	127,891	115,371	10.85%
Net profit margin	13.62%	14.85%	-8.28%
EPS(NT Dollar)	1.61	1.45	11.03%
ROE	6.85%	6.41%	6.86%



Operating revenue / Gross margin

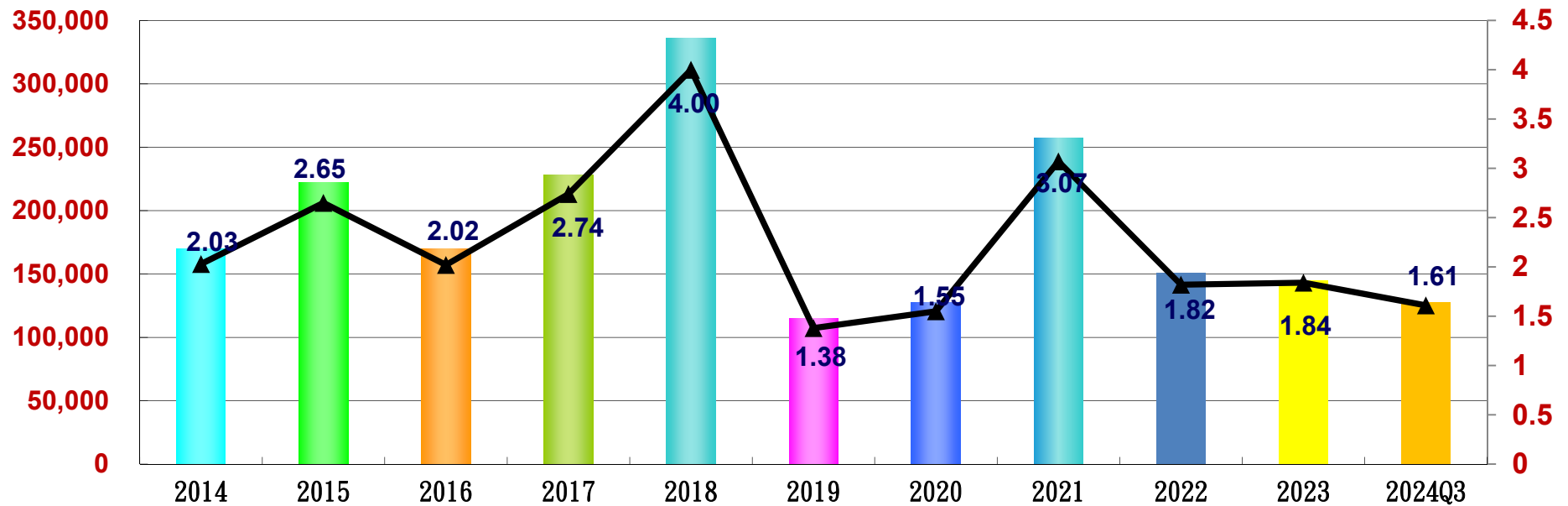
Units : NT\$ Thousand;%



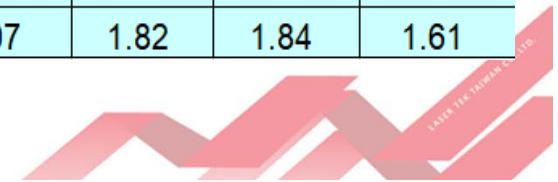
Items	2014	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024Q3
Revenue	1,941,943	1,995,668	2,004,536	2,287,415	2,211,070	1,078,330	1,221,008	1,751,466	1,386,770	1,177,816	935,808
Gross margin	25.70%	26.44%	25.31%	28.20%	29.23%	26.25%	29.75%	30.52%	32.53%	32.85%	32.22%

Net income & EPS

Units : NT\$ Thousand; NT Dollar



Items	2014	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024Q3
Net Income	170,007	222,256	169,726	228,105	335,810	114,914	127,264	257,275	150,538	144,981	127,467
EPS	2.03	2.65	2.02	2.74	4.00	1.38	1.55	3.07	1.82	1.84	1.61





持續創新改善 全員追求卓越

Thank you for coming here today.

LASER TEK, TAIWAN CO., LTD.